

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): A method for capping a Micro-Electromechanical System (MEMS) device, the method comprising:

    forming a cap structure having a bottom side with at least a MEMS cavity, a cut capture cavity surrounding the MEMS cavity, and a cap wall, the cap wall forming an outer wall of the MEMS cavity and an inner wall of the cut capture cavity;

    bonding the cap wall onto a MEMS structure;

filling the cut capture cavity with a protective material; and

    cutting through to the cut capture cavity from a top side of the cap structure to form a cap.

Claim 2 (original): The method of claim 1, wherein forming the cap structure comprises:

    forming the MEMS cavity and the cut capture cavity into the bottom side of the cap structure.

Claim 3 (original): The method of claim 2, wherein forming the MEMS cavity and the cut capture cavity into the bottom side of the cap structure comprises:

    etching the MEMS cavity and the cut capture cavity into the bottom side of the cap structure.

Claim 4 (original): The method of claim 1, wherein forming the cap structure comprises:

forming the cap wall onto the bottom side of the cap structure, the cap wall forming the outside wall of the MEMS cavity and the inside wall of the cut capture cavity.

Claim 5 (original): The method of claim 4, wherein forming the cap wall onto the bottom side of the cap structure comprises:

depositing a cap wall material onto the bottom side of the cap structure to form the cap wall.

Claim 6 (original): The method of claim 1, wherein bonding the cap wall onto the MEMS structure comprises:

applying a bonding material to a bottom side of the cap wall; and  
bonding the bottom side of the cap wall onto the MEMS structure.

Claim 7 (original): The method of claim 6, wherein the bonding material comprises a glass material.

Claim 8 (original): The method of claim 7, wherein applying the bonding material to the bottom side of the cap wall comprises:

screen printing a glass frit material onto the bottom side of the cap wall;  
burning off organic compounds of the glass frit material; and  
glazing the remaining glass frit material to form the glass material.

Claim 9 (original): The method of claim 7, wherein bonding the bottom side of the cap wall onto the MEMS structure comprises:

bonding the bottom side of the cap wall onto the MEMS structure under pressure at a temperature sufficient to melt the glass material.

Claim 10 (currently amended): The method of claim 1, ~~further comprising:~~

— ~~filling wherein the cut capture cavity is filled with [[a]] the protective material prior to cutting through to the cut capture cavity from the top side of the cap structure to form the cap after the cap wall is bonded onto the MEMS structure.~~

Claim 11 (currently amended): The method of claim 1 [[10]], wherein the protective material comprises a wax material.

Claim 12 (currently amended): The method of claim 1 [[10]], further comprising:

removing residual protective material after cutting through to the cut capture cavity from a top side of the cap structure to form the cap.

Claim 13 (Original): The method of claim 1, wherein cutting through to the cut capture cavity from the top side of the cap structure to form the cap comprises cutting through to the cut capture cavity from the top side of the cap structure using at least one of:

- a precision cutting technique;
- a precision grinding technique;
- a laser technique; and
- an etching technique.

Claim 14 (Original): The method of claim 1, wherein the cap structure comprises a silicon material.

Claims 15-18 (canceled).